









PRODUCT DATASHEET



- ► PLCC2 Top View
- ➤ 3528+Lens 3.6t Series
- ► Green (520nm)

N0G51S32BS



3528+Lens Series





3528 + Lens Series

APPLICATIONS:

- **LED Display**
- Indicator
- Traffic Display
- **Decoration Lighting**

FEATURES:

- Package: PLCC2 Black Face SMT Package with Lens
- Forward Current: 50mA Forward Voltage (typ.): 3.1V
- Luminous Intensity (typ.): 20000mcd@50mA
- Colour: Green Wavelength: 520nm Viewing angle: 30°
- **Materials:**
 - Die: InGaN
 - Resin: Epoxy (Water Clear)
 - L/F Finish: Ag Plated
- Operating Temperature: -40~+80°C
- **Storage Temperature:** -40~+85°C **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - **Dominant Wavelength**
- Soldering methods: Reflow soldering Preconditioning: acc. to JEDEC Level 3
- Packing: 12mm tape with max.2000pcs/reel, ø330mm (13'')



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	70	mA
Peak Forward Current Duty 1/8@1KHz	I _{FP}	125	mA
Reverse Voltage	VR	5	V
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	259	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

Electrical & Optical Characteristics (Ta=25°C)

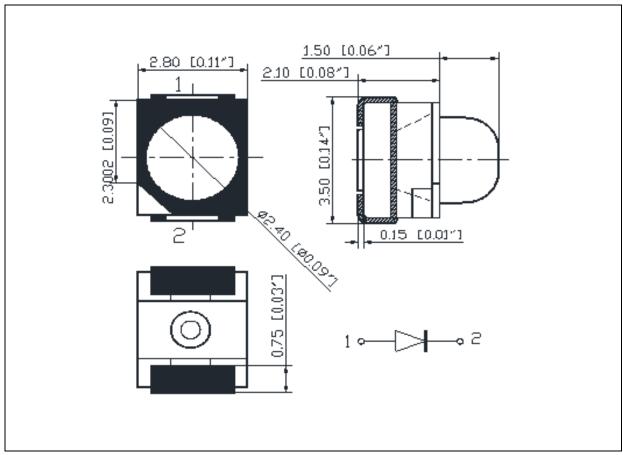
Parameter	Symbol	Values			Unit	Test
Parameter	Зуппоп	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V_{F}	2.8	3.1	3.7	V	I _F =50mA
Luminous Intensity	lv	11200	20000	36000	mcd	I _F =50mA
Dominant Wavelength	λD	515	520	525	nm	I _F =50mA
Peak Wavelength	λ_{P}		515		nm	I _F =50mA
Spectral Half Bandwidth	Δλ		31		nm	I _F =50mA
Viewing Angle	2θ _{1/2}		30		deg	I _F =50mA

^{1.} Luminous intensity (Iv) $\pm 15\%$, Forward Voltage (V_F) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 5\%$



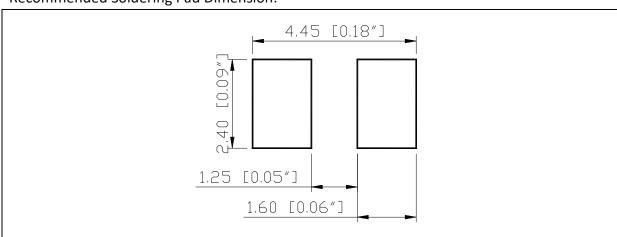
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 50mA):

I	Code	Min.	Max.	Unit
	f	2.8	3.1	
Ī	g	3.1	3.4	V
	h	3.4	3.7	

Luminous Intensity Classifications (I_F = 50mA):

Code	Min.	Max.	Unit
d	11200	14200	
e	14200	18000	
f	18000	22500	mcd
g	22500	28500	
h	28500	36000	

Wavelength Classifications (I_F = 50mA):

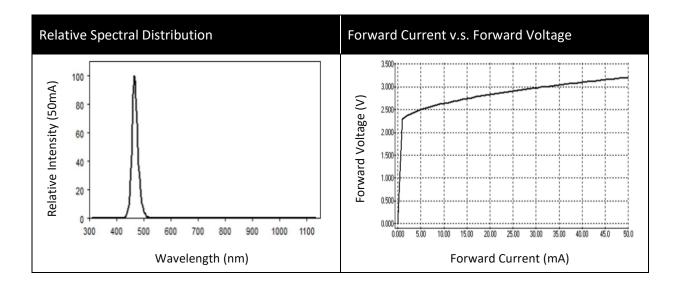
Code	Min.	Max.	Unit
S	515	517.5	
Т	517.5	520	
U	520	522.5	nm
V	522.5	525	

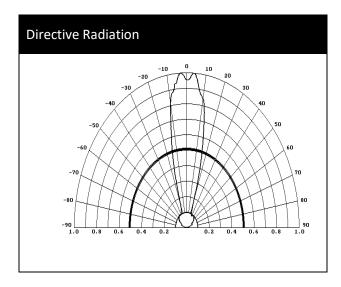
Example Binning Information on Label:

Code	Vf (V)	lv (mcd)	λd (nm)	Test Condition
ggV50	3.1~3.4	22500~28500	522.5~525	nm



ELECTRO-OPTICAL CHARACTERISTICS:

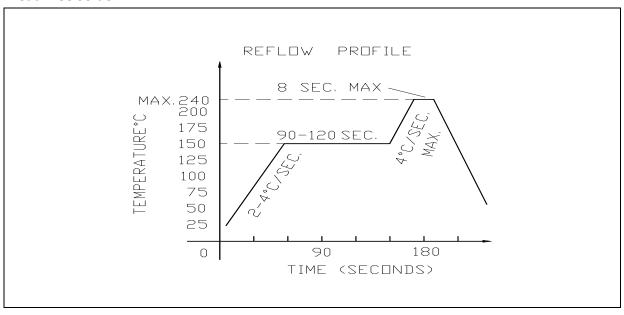






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



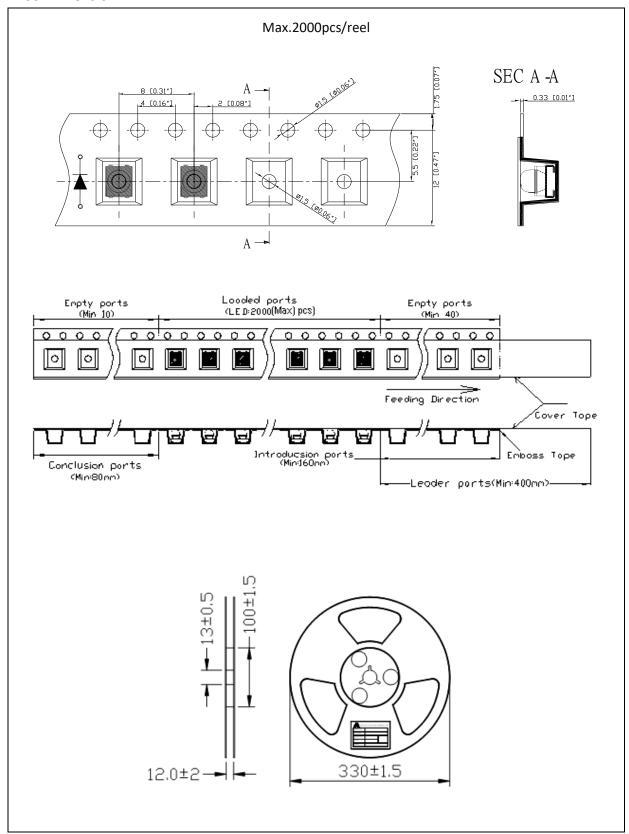
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. The maximum soldering temperature is 240°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

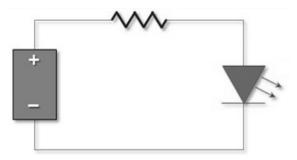
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	30/04/2020	Datasheet set-up.